

PART NO.	GUIDE-POST	RETAINER
20031-...E-#1F	YES	YES
20031-...E-#2F	YES	NO
20031-...E-#3F	NO	YES
20031-...E-#4F	NO	NO

☆EXAMPLE 20031-...*#*F

* MARK MEANS PACKAGE STYLE

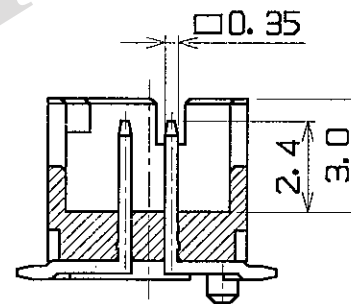
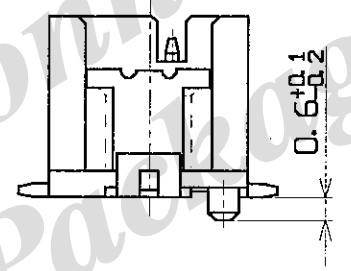
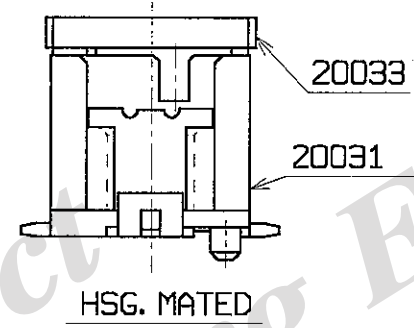
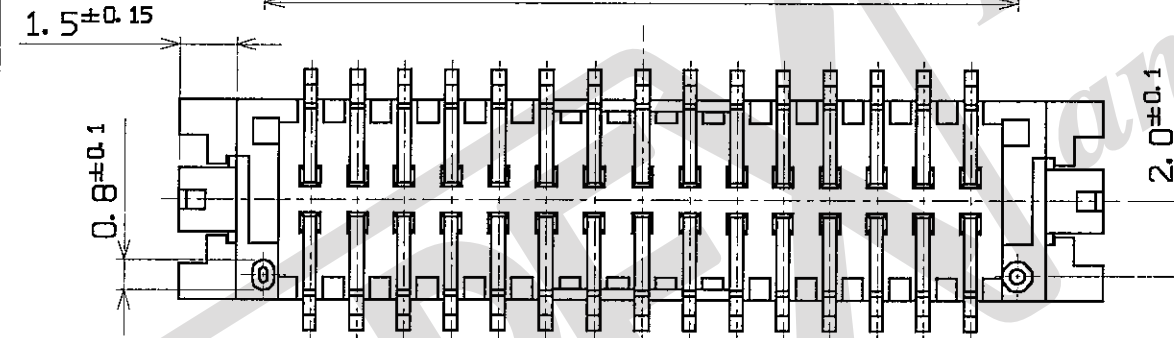
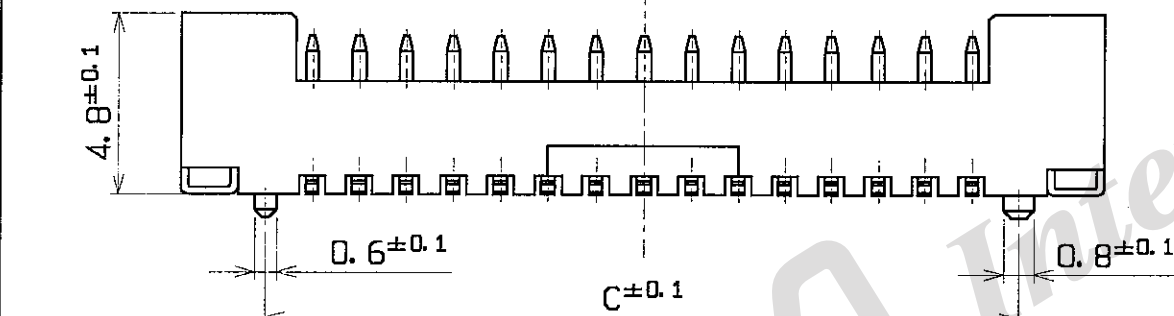
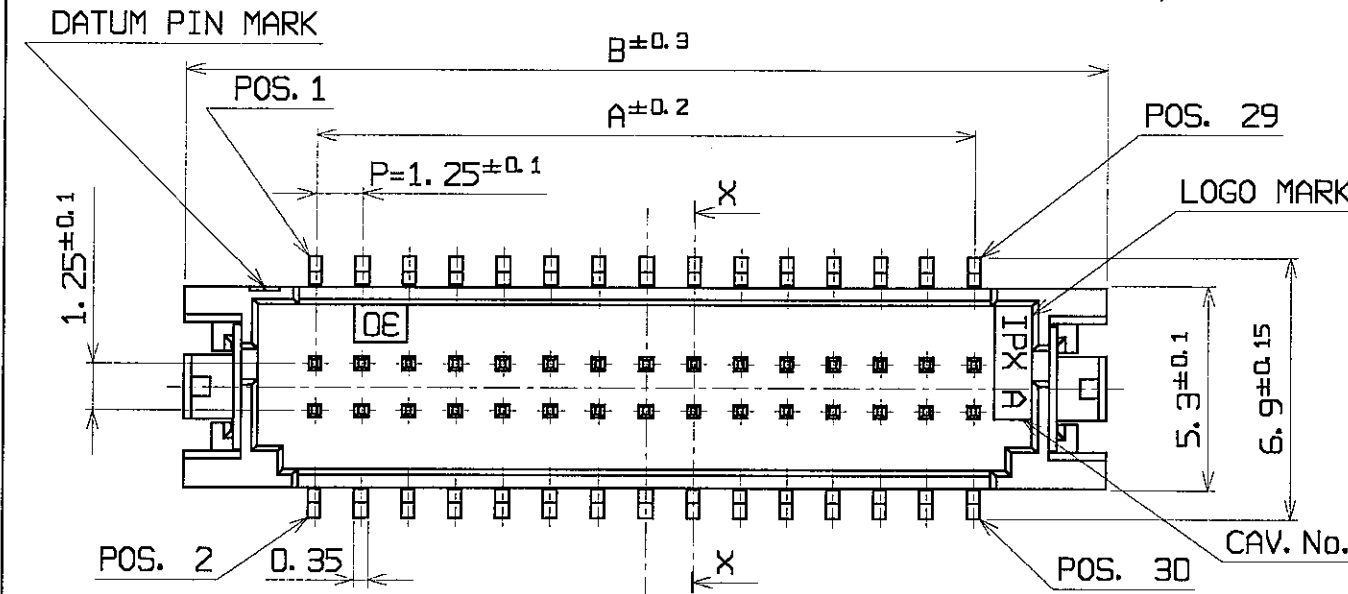
MARK MEANS FINISH

U : TUBE PACKAGE
E : EMBOSS TAPING PACKAGE

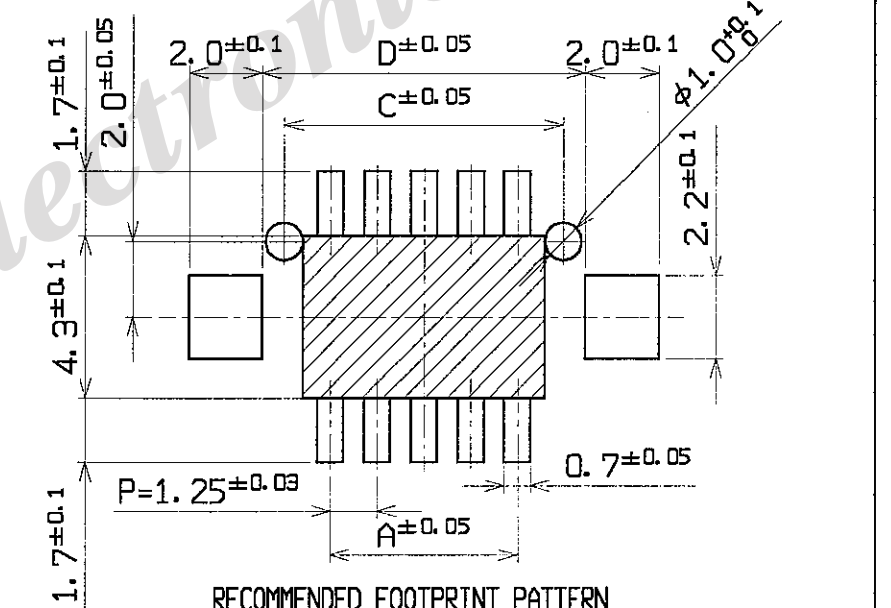
0 : Sn OVER Ni
1 : Au OVER Ni

PART. NO.	POS.	A	B	C	D
20031-010*#*F	10	5.0	12.0	7.5	8.7
20031-012*#*F	12	6.25	13.25	8.75	9.95
20031-020*#*F	20	11.25	18.25	13.75	14.95
◆20031-022*#*F	22	12.5	19.5	15.0	16.2
20031-030*#*F	30	17.5	24.5	20.0	21.2
◆20031-032*#*F	32	18.75	25.75	21.25	22.45
20031-040*#*F	40	23.75	30.75	26.25	27.45
20031-042*#*F	42	25.0	32.0	27.5	28.7
◆20031-050*#*F	50	30.0	37.0	32.5	33.7

◆ MARK MEANS UNDER DEVELOPING.

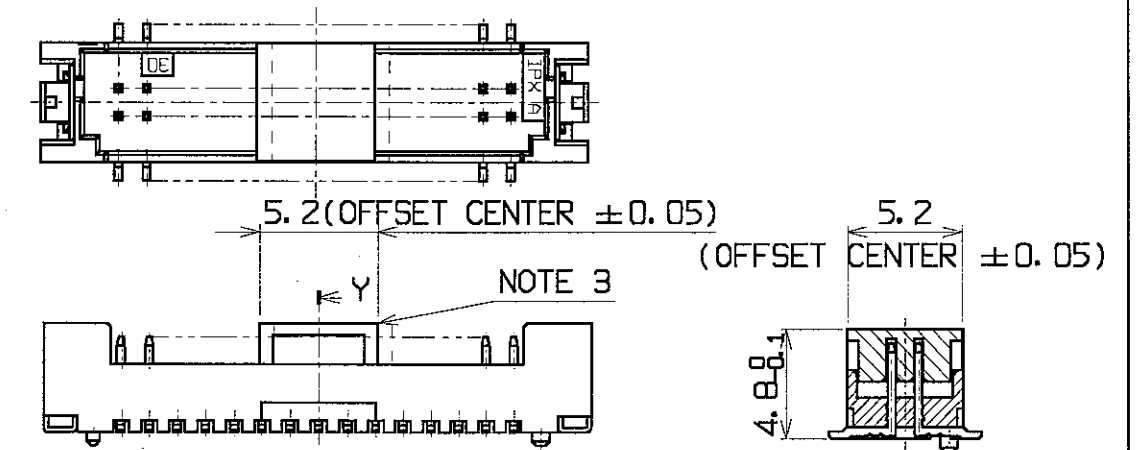


SECT. X-X



RECOMMENDED FOOTPRINT PATTERN

* PATTERN IN THE SHADED AREA MAY TOUCH THE CONTACTS WHEN NO RESIST IS APPLIED.



DIMENSIONS OF VACUUM COVER
EMBOSS TAPING PACKAGE ONLY.

- NOTES
- MATERIAL & FINISH
INSULATOR - LCP (UL94V-0)
CONTACT (STANDARD) - COPPER ALLOY
Sn OVER Ni (UNDER 30 PINS)
Au OVER Ni (30 PINS OR OVER)
RETAINER - COPPER ALLOY
Sn OVER Cu
VACUUM COVER - PA66 (UL94V-0)
 - P/N 20031-...E-#*F : SEE 300-039 OF THE PACKING STANDARD.
P/N 20031-...U-#*F : SEE 300-068 OF THE PACKING STANDARD.
 - VACUUM COVER POSITION
10P, 22P, 30P, 42P, 50P : CENTER (———)
12P, 20P, 30P, 40P : OFFSET CENTER (-----)
(HALF PITCH TO I-PEX MARK SIDE.)

GENERAL TOLERANCE		
6 MAX.	±0.2	
6 OVER MAX. 30	±0.3	
30 OVER MAX. 120	±0.5	
ANGLE	±2°	

DESIGN'D BY M. TSURUSAKI	DATE 01/19/96	I-PEX Interconnect and Packaging Electronics TOKYO, JAPAN	TOL. ±0.3 , ±2'	TITLE DUALOK DUAL TYPE HDR ASS'Y ST-SMT
CHK'D BY Y. H	DATE 02/06/96		SCALE 5/1	UNIT mm
APP'D BY Y. FUKUDA	DATE 02/16/96	CUSTOMER COPY	PROJECTION ①	DWG. No. 20031
REV. RECORD	SERIES No. 2210			SHEET REV. 1/1 13